

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A semiconductor power module comprising:
a metallic base;
an insulating substrate fixedly laminated on the metallic base, the insulating substrate including a plate-like insulating body and a surface conductive layer fixedly laminated on a surface of the plate-like ~~semiconductor~~ insulating body via a surface side fixing member;
a power semiconductor element mounted on the insulating substrate; and
an electrode terminal plate fixed to the insulating substrate via a joint portion,
wherein the surface side fixing member includes [[:]] a first fixing portion for fixing one part of the surface conductive layer located underneath the joint portion of the electrode terminal [[:]], the first fixing portion formed of a first material including a metal, and a second fixing portion for fixing the other part of the surface conductive layer which is not located underneath the joint portion, and
wherein a fixing strength exhibited by the first fixing portion is smaller than that exhibited by the second fixing portion.

Claim 2 (Original): The semiconductor power module as claimed in Claim 1, wherein the first fixing portion is formed by providing a fixing member only on its peripheral portions while its central portion is formed as an unfixed clearance portion.

Claim 3 (Original): The semiconductor power module as claimed in Claim 1, wherein a boundary portion between the first fixing portion and the second fixing portion is tightly sealed.

Claim 4 (Original): The semiconductor power module as claimed in Claim 2, wherein a boundary portion between the first fixing portion and the second fixing portion is tightly sealed.

Claim 5 (Original): The semiconductor power module as claimed in Claim 1, wherein the first fixing portion is quadrangular having four peripheral portions, and one of the four peripheral portions located at a boundary portion with respect to the second fixing portion is not provided with a fixing member but only the remaining three peripheral portions are provided with the fixing member while its central portion is formed as an unfixed clearance portion.

Claim 6 (Currently Amended): The semiconductor power module as claimed in Claim 5, wherein in the three peripheral portions of the first fixing ~~portions~~ portion, a width of an opposite peripheral portion located on an opposite side of the boundary with respect to the second fixing portion is larger than a width of the remaining two peripheral portions of the first fixing portion.

Claim 7 (New): A semiconductor power module comprising:
a metallic base;
an insulating substrate fixedly laminated on the metallic base, the insulating substrate
including a plate-like insulating body and a surface conductive layer fixedly laminated on a
surface of the plate-like insulating body via a surface side fixing member;
a power semiconductor element mounted on the insulating substrate; and
an electrode terminal plate fixed to the insulating substrate via a joint portion,
wherein the surface side fixing member includes a first fixing portion for fixing one
part of the surface conductive layer located underneath the joint portion of the electrode
terminal, and a second fixing portion for fixing the other part of the surface conductive layer
which is not located underneath the joint portion,
a fixing strength exhibited by the first fixing portion is smaller than that exhibited by
the second fixing portion, and
the first fixing portion is quadrangular having four peripheral portions, and one of the
four peripheral portions located at a boundary portion with respect to the second fixing
portion is not provided with a fixing member but only the remaining three peripheral portions
are provided with the fixing member while its central portion is formed as an unfixed
clearance portion.

Claim 8 (New): The semiconductor power module as claimed in Claim 7, wherein in
the three peripheral portions of the first fixing portion, a width of an opposite peripheral
portion located on an opposite side of the boundary with respect to the second fixing portion
is larger than a width of the remaining two peripheral portions of the first fixing portion.